

Notification Number:	20260827003.0	Notification Issued	August 31, 2026
Datasheet for LM317L			

Change Type(s)	Data Sheet/Electrical Specification
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Notification Details

Description of Change:	
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.	
 SLCS144G – JULY 2004 – REVISED AUGUST 2026 LM317L	
Changes from Revision F (December 2024) to Revision G (August 2026)	Page
• Updated legacy and new chip information throughout the document.....	1
• Removed output voltage range of the legacy chip from the <i>Features</i> section.....	1
• Changed the input regulation per input voltage change from 0.01% to 0.007% in the <i>Features</i> section to reflect new chip (CSO: RFB) specs.....	1
• Changed the typical ripple rejection at 120Hz spec from 80dB to 71.5dB in the <i>Features</i> section to reflect new chip (CSO: RFB) specs.....	1
• Removed ripple rejection at 100kHz spec from the <i>Features</i> section.....	1
• Added device package options to the <i>Features</i> section.....	1
• Updated <i>Applications</i> section.....	1
• Updated the <i>Description</i> section to reflect new chip (CSO: RFB) specs.....	1
• Changed output voltage maximum from 32V to 37V in the <i>Description</i> section to reflect new chip (CSO: RFB) specs.....	1
• Added new chip (CSO: RFB) specs to the Absolute Maximum Ratings.....	4
• Added new chip (CSO: RFB) specs to the ESD Ratings.....	4
• Added new chip (CSO: RFB) specs to the Recommended Operating Conditions.....	4
• Added new chip (CSO: RFB) specs to the Thermal Information.....	5
• Updated Thermal Information to two tables for clarity.....	5
• Added new chip (CSO: RFB) specs to the Electrical Characteristics.....	5
• Updated titles of <i>Typical Characteristics</i> graphs for legacy chip (CSO: SHE & CSO: TID).....	7
• Added <i>Typical Characteristics</i> graphs for new chip (CSO: RFB).....	7
• Updated <i>Overview</i> section to reflect new chip (CSO: RFB) specs.....	9
• Removed mention of specific output voltage range and bias current in the <i>Overview</i> section, instead added a reference the <i>Electrical Characteristics</i> table, where the specs can be found.....	9
• Updated <i>NPN Darlington Output Drive</i> with link to the <i>Recommended Operating Conditions</i>	10
• Updated <i>Operation With Low Input Voltage</i> with a link to the <i>Recommended Operating Conditions</i>	10
• Updated <i>Operation at Light Loads</i> with a link to the <i>Electrical Characteristics</i>	10
• Updated <i>Operation in Self Protection</i> for clarity.....	10
• Updated the maximum input range example value from 32V to 37V in the <i>Design Requirements</i> to reflect new chip (CSO: RFB) specs.....	11
• Updated <i>Adjustment Terminal Capacitor</i> section to mention C_{ADJ}	12
• Updated adjustment current from 50μA to 44μA in the <i>Output Voltage</i> section to reflect new chip (CSO: RFB) specs.....	12
• Changed position of <i>Input Short Protection</i> to before <i>Ripple Rejection</i> within the <i>Detailed Design Procedure</i> ..	

.....	12
• Updated <i>Ripple Rejection</i> with a link to the <i>Adjustment Terminal Capacitor</i> section.....	12
• Updated <i>Application Curve</i> to specify legacy chip performance.....	12
• Added note to <i>0V to 30V Regulator Circuit</i>	13
• Added note to <i>Slow-Turn On 15V Regulator Circuit</i>	14
• Added note to <i>Current-Limited 6V Charger</i>	15
• Added note to <i>High-Current Adjustable Regulator</i>	16
• Updated the maximum input voltage from 32V to 37V in the <i>Power Supply Recommendations</i> section to reflect new chip (CSO: RFB) specs.....	17
• Added a link to the <i>Recommended Operating Conditions</i> table in the <i>Power Supply Recommendations</i> section.....	17
• Updated <i>Layout Guidelines</i> to give more detailed guidance about capacitor placement.....	17
• Added SOIC layouts to the <i>Layout Example</i> section.....	17
• Updated the <i>Device Nomenclature</i> for clarity, included distinction based on CSO.....	19

The datasheet number will be changing.

Device Family	Change From:	Change To:
LM317L	SLCS144F	SLCS144G

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/LM317L>

Reason for Change:	To accurately reflect device characteristics
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Anticipated impact on Form, Fit, Function, Quality or Reliability:	None
Changes to product identification resulting from this PCN:	None

Products Affected:			
LM317LCD.A	LM317LIDRG4	LM317LIDR.A	LM317LID.A
LM317LIDR	LM317LIDRG4.A	LM317LCD	LM317LIPW.A
LM317LILP.A	LM317LIPW	LM317LCLPR	LM317LIPWR
LM317LILPR	LM317LILP	LM317LCPWR.A	LM317LCDR
LM317LILPR.A	LM317LIPWR.A	LM317LID	LM317LCDRG4.A
LM317LCDR.A	LM317LCDR.B	LM317LCDRG4	LM317LCPW
LM317LCLP	LM317LCLPR.A	LM317LIDRG4.B	LM317LCPWR
LM317LCLPRE3	LM317LCPW.A	LM317LCLP.A	LM317LCPWRG4
LM317LIDR.B	LM317LCPWE4		

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Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

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